

Hardware Market for Mobile 3D Sensing Will Expand at a CAGR of 209% From 2017 to 2020, Says TrendForce

2017-09-11 [Jason Tsai](#)

TrendForce anticipates that from 2017 onward, the market for 3D sensing solutions used in mobile devices will witness leaping growth. The total value of the global market for 3D sensing modules used in mobile devices is estimated to reach US\$1.5 billion in 2017 and is forecast to grow at a massive CAGR of 209% to around US\$14 billion in 2020. Note that the 3D sensing module that is being discussed includes IR transmitter and receiver components.

About TrendForce

TrendForce is a global provider of the latest development, insight, and analysis of the technology industry. Having served businesses for over a decade, the company has built up a strong base membership base of 435,000 subscribers. TrendForce has established a reputation as an organization that offers insightful and accurate analysis of the technology industry through five major research divisions: DRAMXchange, WitsView, LEDinside, EnergyTrend and Topology. Founded in Taipei, Taiwan in 2000, TrendForce has extended its presence in China since 2004 with offices in Shenzhen and Beijing. For more details about TrendForce, please visit www.trendforce.com

Major research divisions:

DRAMeXchange focuses on memory, storage and the consumer electronics industry including PC DRAM, Mobile DRAM, Server DRAM, NAND Flash, SSD and smartphone.

WitsView offers comprehensive coverage of the display industry from upstream components, midstream panels/touch modules to downstream system integrators, brands and channels.

LEDinside covers all aspects of the LED supply chain from upstream equipment/materials, midstream chip/packaging to the downstream backlight and lighting market.

EnergyTrend specializes in green energy research, such as solar energy, lithium battery, energy storage systems and xEVs.

Topology studies structural trends of technology industries in the Greater China Region and beyond, focusing on semiconductors, photovoltaic technology, telecommunications, and IA.

Media Contact

Pinchun Chou +886-2-8978-6488 ext.669 PinchunChou@TrendForce.com

Lindsay Hou +886-2-8978-6488 ext.667 Lindsayhou@TrendForce.com

Source URL: Trendforce - Press Center [Hardware Market for Mobile 3D Sensing Will Expand at a CAGR of 209% From 2017 to 2020, Says TrendForce](#)